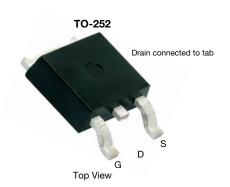


www.vishay.com

Vishay Siliconix

N-Channel 150 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	150
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0447
Q _g typ. (nC)	10.5
I _D (A)	42 ^d
Configuration	Single

FEATURES

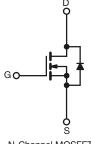
- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



FREE

APPLICATIONS

- · Boost converter
- · LED backlighting
- · Synchronous rectification
- Power supplies
- DC/AC inverter



N-Channel MOSFET

ORDERING INFORMATION	
Package	TO-252
Lead (Pb)-free and halogen-free	SUD80460E-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	150	V	
Gate-source voltage		V _{GS}	± 20	V	
Continuous drain current	T _C = 25 °C		42 ^d		
	T _C = 125 °C	l _D	18.1		
Pulsed drain current (t = 100 μs)		I _{DM}	40	A	
Continuous source-drain diode current		I _S	42 ^d		
Single pulse avalanche current ^a	. 0.4	I _{AS}	25		
Single pulse avalanche energy ^a	L = 0.1 mH	E _{AS}	31.25	mJ	
Maximum power dissipation	T _C = 25 °C	Б	65.2 ^b	w	
	T _C = 125 °C	P _D	21.7 ^b	VV	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	*0	
Soldering recommendations (peak temperature) c			260	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	MAXIMUM	UNIT	
Maximum junction-to-ambient (PCB mount) °		R _{thJA}	50	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	2.3]	

Notes

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).
- d. Package limited.



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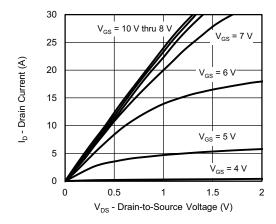
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			1		l		
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	150	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2	-	4	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	250	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 150 V, V _{GS} = 0 V	-	-	1	μΑ	
		V _{DS} = 150 V, V _{GS} = 0 V, T _J = 125 °C	-	-	150		
		V _{DS} = 150 V, V _{GS} = 0 V, T _J = 175 °C	-	-	5	mA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α	
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 10 V, I _D = 8.3 A	-	0.0372	0.0447	Ω	
Forward transconductance a	9 _{fs}	V _{DS} = 15 V, I _D = 8.3 A	-	11	-	S	
Dynamic ^b				•			
Input capacitance	C _{iss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	-	560	-		
Output capacitance	C _{oss}		-	148	-	pF	
Reverse transfer capacitance	C _{rss}		-	8	-		
Total gate charge	Qg		-	10.5	16	nC	
Gate-source charge	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 8.3 \text{ A}$	-	2.7	-		
Gate-drain charge	Q _{gd}		-	3.1	-		
Gate resistance	Rg	f = 1 MHz	1.44	7.2	14.4	Ω	
Turn-on delay time	t _{d(on)}		-	8	16		
Rise time	t _r	$V_{DD} = 75 \text{ V}, R_L = 10.7 \Omega, I_D \cong 7 \text{ A},$	-	20	30		
Turn-off delay time	t _{d(off)}	V_{GEN} = 10 V, R_g = 1 Ω	-	15	25	ns	
Fall time	t _f		-	30	50		
Drain-Source Body Diode Characteristic	cs			•			
Pulse diode forward current (t = 100 μs)	I _{SM}		-	-	42	Α	
Body diode voltage	V _{SD}	I _F = 7 A, V _{GS} = 0 V	-	0.85	1.5	V	
Body diode reverse recovery time	t _{rr}		-	68	102	ns	
Body diode reverse recovery charge	Q _{rr}	1 7 A di/d+ 100 A/:	-	0.21	0.32	μC	
Reverse recovery fall time	t _a	I _F = 7 A, di/dt = 100 A/μs	-	56	-		
Reverse recovery rise time	t _b		-	12	-	ns	
Body diode peak reverse recovery charge	I _{RM(REC)}		-	5.5	10	Α	

Notes

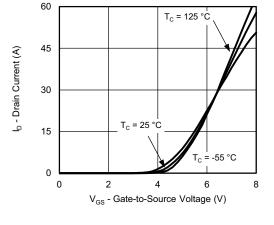
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

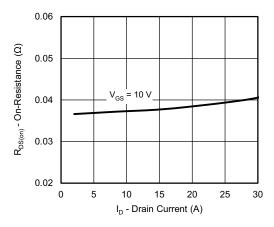




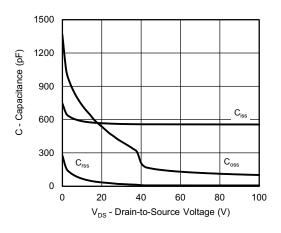
Output Characteristics



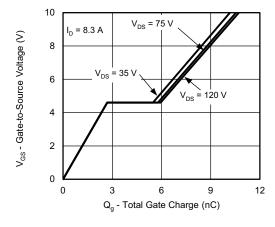
Transfer Characteristics



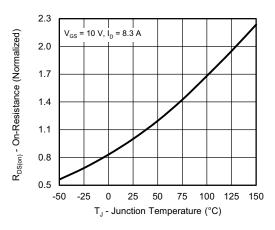
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

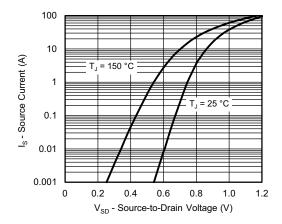


Gate Charge

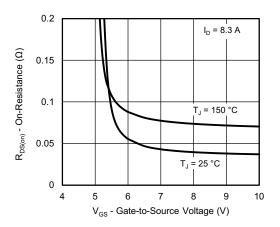


On-Resistance vs. Junction Temperature

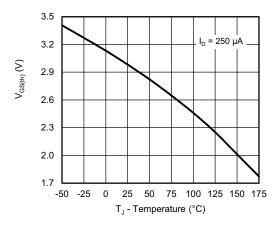




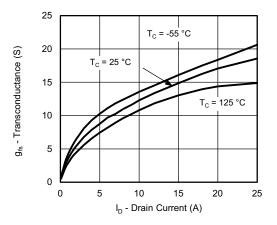
Source-Drain Diode Forward Voltage



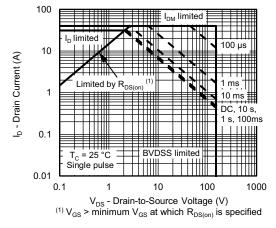
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

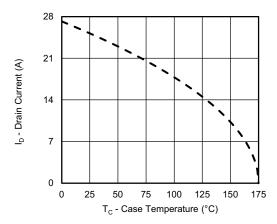


Transconductance

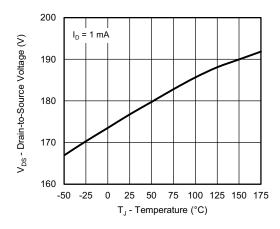


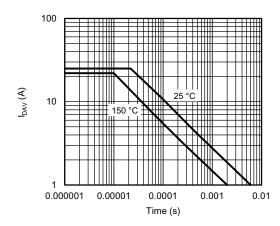
Safe Operating Area, Junction-to-Ambient





Current Derating a





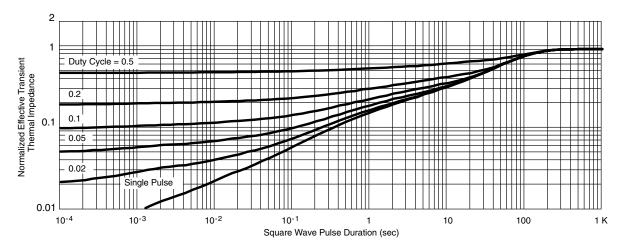
Drain Source Breakdown vs. Junction Temperature

 I_{DAV} vs. Time

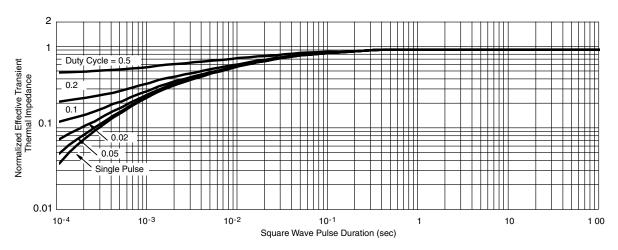
Note

a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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